

AMENDMENTS TO THE CLAIMS

Please amend claims 1, 4, 6, 9, 12, 21, and cancel claims 2, 10, 19, 23, such that the status of the claims is as follows:

1.(**Currently Amended**) A microelectromechanical component formed of silicon, the component comprising:

a feature on the component which is subjected to a repeated mechanical stress; and means for increasing robustness of the feature by covering the feature with a ductile material having a thickness of greater than about 10 microns to absorb repeated stress and to reduce breakage or chipping.

2.(**Canceled**)

3.(**Original**) The component of claim 2 wherein the ductile material comprises a metal.

4.(**Currently Amended**) The component of claim 1 wherein means for increasing the robustness of the feature further comprises a coating on the component ~~with a~~ comprising a ductile material, wherein the coating has a thickness of greater than 10 microns.

5.(**Original**) The component of claim 4 wherein the ductile material comprises a metal.

6.(**Currently Amended**) A microcomponent formed of silicon, the microcomponent comprising:
a feature on the microcomponent which is subjected to a mechanical stress; and
a ductile material coating the feature to increase robustness of the microcomponent,
wherein the ductile material has a thickness of greater than about 10 microns,
and absorbs mechanical stress to reduce chipping or breaking near the feature
which is subjected to the mechanical stress.

7.(Original) The microcomponent of claim 6 wherein the ductile material comprises a metal.

8.(Original) The microcomponent of claim 7 and further comprising a seed layer to facilitate the ability of the metal to coat the feature.

9.(Currently Amended) The microcomponent of claim 7 wherein the metal has a thickness of about ± 20 microns.

10.(Canceled)

11.(Original) The microcomponent of claim 6 and further comprising a ductile material coating substantially the entire surface of the micro component.

12.(Currently Amended) A method of increasing the robustness and absorbing mechanical stress of an area on a microelectromechanical component to reduce chipping or breaking of the component, the method comprising:

forming the microelectromechanical component from silicon; and

coating a selected area on the component which is subjected to a mechanical stress with a ductile material so that the ductile material has a thickness of greater than about ten microns.

13.(Original) The method of claim 12 wherein forming the component from silicon comprises forming a plurality of components from a silicon wafer.

14.(Original) The method of claim 13 wherein coating the component with a ductile material comprises coating a preselected area of the component with a metal.

15.**(Original)** The method of claim 14 wherein coating a preselected area of the component with a metal comprises:

- applying photo resist to the component to define an area to which the metal will be applied;
- depositing a seed layer on the component;
- removing the photo resist so that the seed layer remains only in the area to which the metal will be applied; and
- applying a metal coating to the seed layer.

16.**(Original)** The method of claim 15 wherein applying the metal coating to the seed layer comprises using a chemical vapor deposition process.

17.**(Original)** The method of claim 15 wherein applying the metal coating to the seed layer comprises using an electroplating process.

18.**(Original)** The method of claim 15 wherein applying the metal coating to the seed layer comprises using a sputtering process.

19.**(Canceled)**

20.**(Original)** The method of claim 15 wherein applying the metal coating comprises applying the metal coating to a thickness of up to about 20 microns.

21.**(Currently Amended)** A micro-electro-mechanical component formed of silicon, the component comprising:

- a feature on the component which is subjected to a mechanical stress; and
- a coating on the feature to increase the robustness thereof by covering the feature and absorbing repeated stress to reduce breakage or chipping, the coating

comprising a ductile metal having a thickness of greater than about 10 microns.

22.**(Previously Added)** The micro-electro-mechanical component of claim 21 further comprising a seed layer to facilitate the ability of the metal to coat the feature.

23.**(Canceled)**

24.**(Previously Added)** The micro-electro-mechanical component of claim 21 wherein the ductile metal coating the feature prevents the silicon from chipping or breaking near the feature which is subjected to a mechanical stress.

25.**(Previously Added)** The micro-electro-mechanical component of claim 21 wherein the coating comprising a ductile metal coats substantially the entire surface of the component.